

TO-5050SWNQ-F3

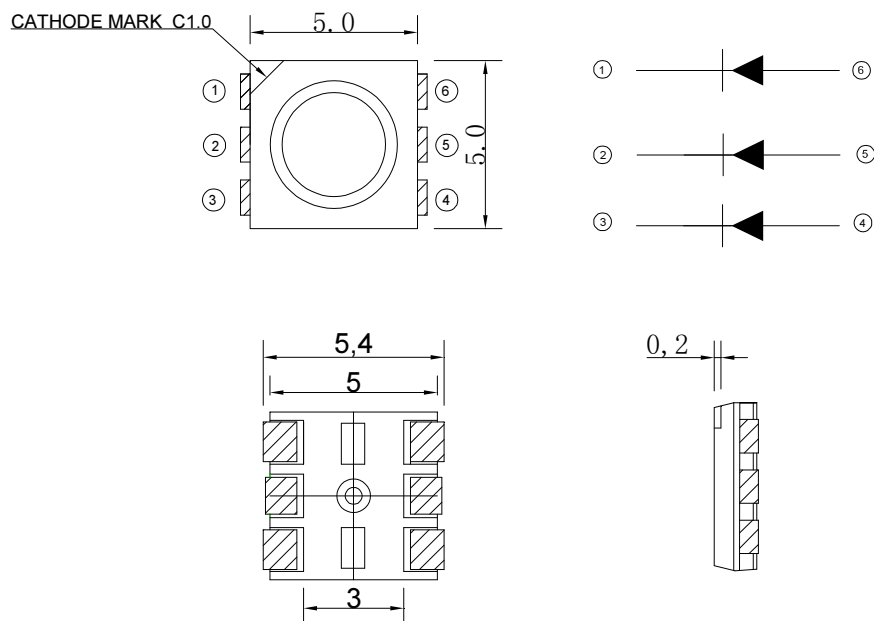
Surface Mount Device LED

Part Number	Chip		Lens Color
	Material	Source Color	
TO-5050SWNQ-F3	InGaN	Ultra White	Yellow Diffused

Features

- IC compatible
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow solder process
- Top view type
- Package in 12 mm tape on 7" diameter reel
- RoHS compliant
- Moisture sensitivity level: level 3

Dimensions



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.1 mm unless otherwise noted.

Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	200	mA
Power Dissipation	315	mW
Continuous Forward Current	75	mA
Reverse Voltage	5	V
Operating Temperature Range	-40°C to +80°C	
Storage Temperature Range	-40°C to +100°C	
IR Reflow Soldering Profile For Lead Free Soldering	260°C for 10 sec	

Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	5243		9060	mcd	I _F =60mA
Color Temperature	T _c		6000		K	I _F =60mA
Total Flux	Φ _V		21		lm	I _F =60mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =60mA
Forward Voltage	V _F		3.2		V	I _F =60mA
Reverse Current	I _R			10	μA	V _R =5V
Chromaticity Coordinates	X		0.325			I _F =60mA
Chromaticity Coordinates	Y		0.34			I _F =60mA